

Title (en)

Semiconductor wafer treatment by brushing before bonding

Title (de)

Bürsten einer Halbleiterscheibe vor dem Kleben

Title (fr)

Traitement par brossage d'une plaquette semiconductrice avant collage

Publication

EP 1473765 B1 20130605 (FR)

Application

EP 04291100 A 20040429

Priority

FR 0305236 A 20030429

Abstract (en)

[origin: EP1473765A2] Gluing of two platelets at the level of two gluing surfaces respectively comprises: (a) activation of at least one gluing surface; (b) putting the gluing surfaces into contact. The activation stage is obtained by brushing the gluing surface. An independent claim is also included for the removal of a layer of semiconducting material from a donor platelet which incorporates a stage using this method of gluing two platelets together.

IPC 8 full level

H01L 21/762 (2006.01); **H01L 21/02** (2006.01); **H01L 21/20** (2006.01); **H01L 21/304** (2006.01); **H01L 27/12** (2006.01)

CPC (source: EP)

H01L 21/02052 (2013.01); **H01L 21/02096** (2013.01); **H01L 21/2007** (2013.01); **H01L 21/76251** (2013.01); **H01L 21/76254** (2013.01); **H01L 21/76259** (2013.01)

Cited by

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DOCDB simple family (publication)

EP 1473765 A2 20041103; **EP 1473765 A3 20051228**; **EP 1473765 B1 20130605**; FR 2854493 A1 20041105; FR 2854493 B1 20050819; JP 2005142524 A 20050602; JP 4549726 B2 20100922

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EP 04291100 A 20040429; FR 0305236 A 20030429; JP 2004136254 A 20040430